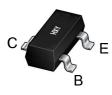


FEATURES

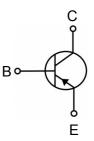
- Collector Current: I_C=0.2A
- Power Dissipation of 250mw





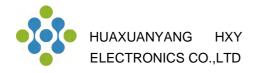
Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBT3906	SOT-23	2A	3000



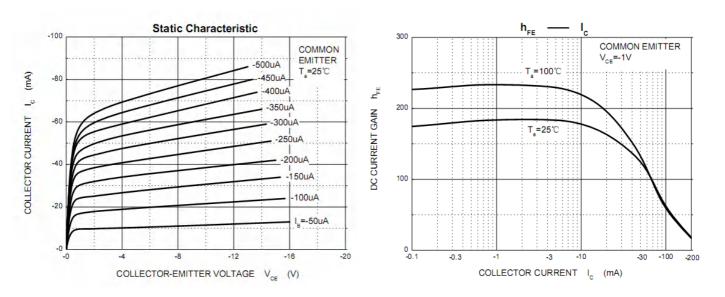
MAXIMUM RATINGS (Ta=25 unless otherwise noted)

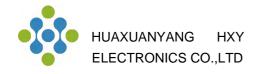
Parameter	Symbol	Limit	Unit	
Collector-Base Voltage	V _{CBO}	-40	V	
Collector-Emitter Voltage	V _{CEO}	-40	V	
Emitter-Base Voltage	V _{EBO}	-5	V	
Collector Current	Ι _c	-200	mA	
Collector Power Dissipation	Pc	200	mW	
Thermal Resistance From Junction To Ambient	R _{OJA}	625	°C/W	
Junction Temperature	Tj	150	°C	
Storage Temperature	T _{stg}	-55~+150	°C	

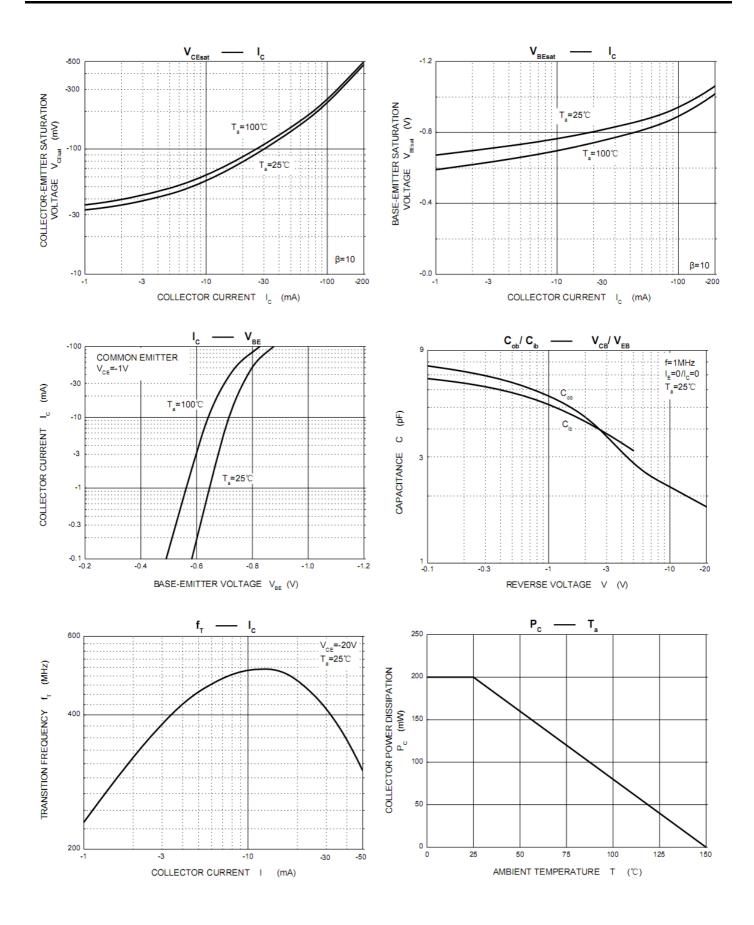


Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =-10μΑ, I _E =0	-40		V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C = -1mA, I _B =0	-40		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = -10μΑ, I _C =0	-5		V
Collector cut-off current	I _{CBO}	I _{CBO} V _{CB} = -40 V, I _E =0		-100	nA
Collector cut-off current	tor cut-off current I _{CEX} V _{CE} =-30V, V _{BE(off)} =-3V			-50	nA
Emitter cut-off current	I _{EBO}	V _{EB} = -5V, I _C =0		-100	nA
	h _{FE1}	V _{CE} =-1V, I _C = -10mA	100	300	
DC current gain	h _{FE2}	V _{CE} = -1V, I _C =-50mA	60		
	h _{FE3}	V _{CE} = -2V, I _C =-100mA	30		
Collector-emitter saturation voltage	V _{CE(sat)1}	I _C =-50mA, I _B =-5mA		-0.3	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C = -50mA, I _B =-5mA		-0.95	V
Transition frequency	f _T	V _{CE} =-20V,I _C =-10mA,f=100MHz	300		MHz
Delay Time	td	V _{CC} =-3V,V _{BE} =-0.5V		35	nS
Rise Time	tr	I _C =-10mA, I _{B1} =I _{B2} =-1mA		35	nS
Storage Time	ts	V _{CC} =-3V,I _C =-10mA		225	nS
Fall Time	tf	I _{B1} =I _{B2} =-1mA		75	nS

Typical Characteristics

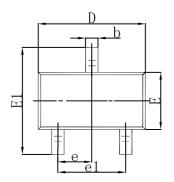


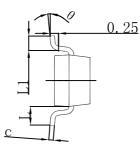


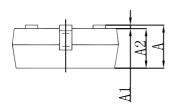




SOT-23 Package Outline Dimensions

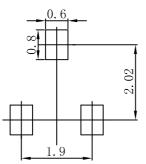






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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